TECHNICAL DATA SHEET

QSil 7750
Thermally conductive material

Key Features

- 100% solids, no solvents
- Excellent physical properties
- Low compression set
- Excellent adhesion when used with a primer

Application

Roller applications

Revision Date	14 Oct 2021
Revision No	2
Download Date	24 Apr 2024

Property	Test Method	Value
Uncured Product		
Cure Profile		**15 min at 150°C followed by 4 hrs at 200°C**
Cure Type		**Addition**
Density A	BS ISO 2781	**1.75**
Density B	BS ISO 2781	**1.75**
Mix Ratio By Weight		**1:1**
Rheology		**Liquid**
Snap Time to Become a Semi Solid at 25°C/77°F		**>18 hr**
Viscosity Mixed	Brookfield	**80000 cP**
Cured Product		
Color		**Red**
Elongation at Break	ISO 37	**185 %**
Hardness Shore A	ASTM D 2240-95	**50**
Max Working Temp		**204 °C / 399 °F**
Min Working Temp		**-55 °C / -67 °F**
Tear Resistance (N/mm)	BS ISO 34-1	**10.41 N/mm / 59 ppi**
Tensile Strength	ISO 37	**3.62 N/mm2 / 525 psi**
Thermal Conductivity		**~0.75 W/mK**
Storage		
Max Storage Temperature		**38 °C / 100 °F**
Shelf Life		**24 mths**

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